



**N-Channel Depletion-Mode Vertical DMOS FETs**

**Ordering Information**

BV <sub>DSX</sub> / BV <sub>DGX</sub>	R <sub>DS(ON)</sub> (max)	I <sub>DSS</sub> (min)	Order Number / Package	
			TO-92	Die
400V	6.0Ω	300mA	DN2640N3	DN2640ND

**Features**

- High input impedance
- Low input capacitance
- Fast switching speeds
- Low on resistance
- Free from secondary breakdown
- Low input and output leakage

**Applications**

- Normally-on switches
- Solid state relays
- Converters
- Linear amplifiers
- Constant current sources
- Power supply circuits
- Telecom

**Absolute Maximum Ratings**

Drain-to-Source Voltage	BV <sub>DSX</sub>
Drain-to-Gate Voltage	BV <sub>DGX</sub>
Gate-to-Source Voltage	± 20V
Operating and Storage Temperature	-55°C to +150°C
Soldering Temperature*	300°C

\* Distance of 1.6 mm from case for 10 seconds.

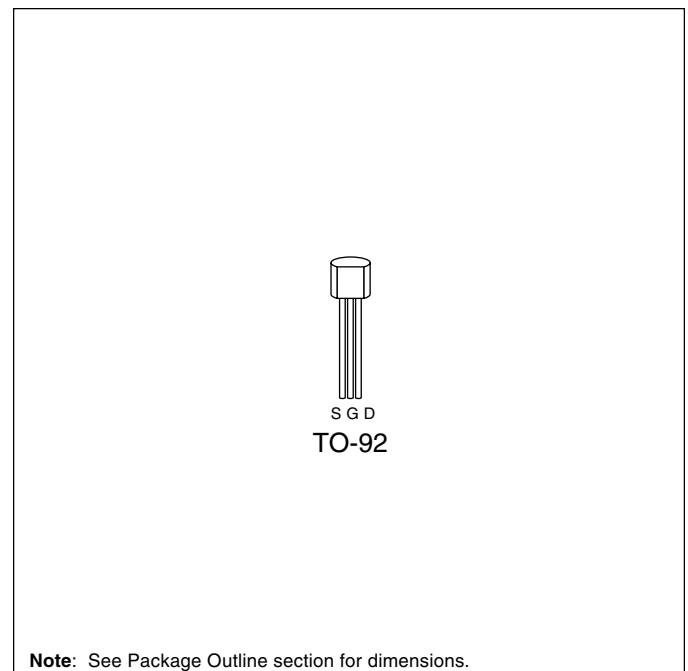
**Advanced DMOS Technology**

These depletion-mode (normally-on) transistors utilize an advanced vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces devices with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

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**Package Options**



## Thermal Characteristics

Package	$I_D$ (continuous)*	$I_D$ (pulsed)	Power Dissipation @ $T_C = 25^\circ\text{C}$	$\theta_{JC}$ $^\circ\text{C/W}$	$\theta_{JA}$ $^\circ\text{C/W}$	$I_{DR}^*$	$I_{DRM}$
TO-92	250mA	600mA	1.0W	125	170	250mA	600mA

\*  $I_D$  (continuous) is limited by max rated  $T_J$ .

**- OBSOLETE -**

## Electrical Characteristics (@ $25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Min	Typ	Max	Unit	Conditions
$BV_{DSX}$	Drain-to-Source Breakdown Voltage	400			V	$V_{GS} = -5V, I_D = 1.0\text{mA}$
$V_{GS(OFF)}$	Gate-to-Source OFF Voltage	-1.0		-3.5	V	$V_{DS} = 25V, I_D = 10\mu\text{A}$
$\Delta V_{GS(OFF)}$	Change in $V_{GS(OFF)}$ with Temperature			4.5	mV/ $^\circ\text{C}$	$V_{DS} = 25V, I_D = 10\mu\text{A}$
$I_{GSS}$	Gate Body Leakage Current			100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
$I_{D(OFF)}$	Drain-to-Source Leakage Current			10	$\mu\text{A}$	$V_{GS} = -10V, V_{DS} = \text{Max Rating}$
				1.0	mA	$V_{GS} = -10V, V_{DS} = 0.8 \text{ Max Rating}$ $T_A = 125^\circ\text{C}$
$I_{DSS}$	Saturated Drain-to-Source Current	300			mA	$V_{GS} = 0V, V_{DS} = 25V$
$R_{DS(ON)}$	Static Drain-to-Source ON-State Resistance			6.0	$\Omega$	$V_{GS} = 0V, I_D = 150\text{mA}$
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with Temperature			1.1	%/ $^\circ\text{C}$	$V_{GS} = 0V, I_D = 150\text{mA}$
$G_{FS}$	Forward Transconductance	300			$\text{m}\bar{\text{S}}$	$I_D = 200\text{mA}, V_{DS} = 10V$
$C_{ISS}$	Input Capacitance			750	pF	$V_{GS} = -10V, V_{DS} = 25V$ $f = 1 \text{ MHz}$
$C_{OSS}$	Common Source Output Capacitance			75		
$C_{RSS}$	Reverse Transfer Capacitance			15		
$t_{d(ON)}$	Turn-ON Delay Time			15	ns	$V_{DD} = 25V,$ $I_D = 200\text{mA},$ $R_{GEN} = 10\Omega$
$t_r$	Rise Time			20		
$t_{d(OFF)}$	Turn-OFF Delay Time			25		
$t_f$	Fall Time			25		
$V_{SD}$	Diode Forward Voltage Drop			1.8	V	$V_{GS} = -10V, I_{SD} = 200\text{mA}$
$t_{rr}$	Reverse Recovery Time		800		ns	$V_{GS} = -10V, I_{SD} = 1.0A$

### Notes:

- All D.C. parameters 100% tested at  $25^\circ\text{C}$  unless otherwise stated. (Pulse test: 300 $\mu\text{s}$  pulse, 2% duty cycle.)
- All A.C. parameters sample tested.

## Switching Waveforms and Test Circuit

